High Accuracy Advanced Laser Marking

DB Series

Designed for Advanced Thinning Substrate Solution

Feature

Optimal ability of handler for large warpage

- Advanced solution for thinning substrate with large warpage
- Stage design is easy to handle the warpage between 1 ~ 10um

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Enhance accuracy design with outstanding throughput performance

- Bottom V.P.S(Vision Position System) enhance marking accuracy within ± 0.05mm
- Dual stage design performs outstanding throughput and change over time < 10 min

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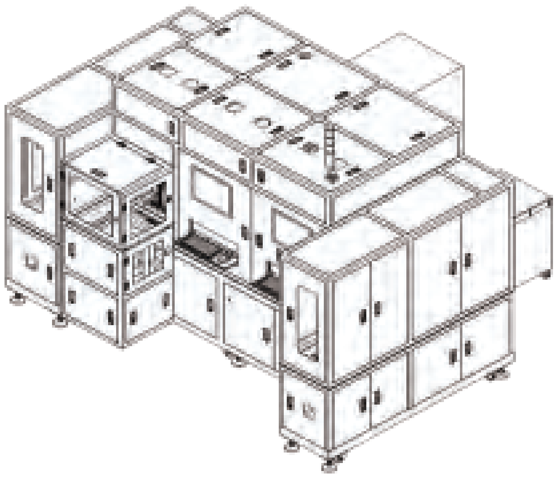
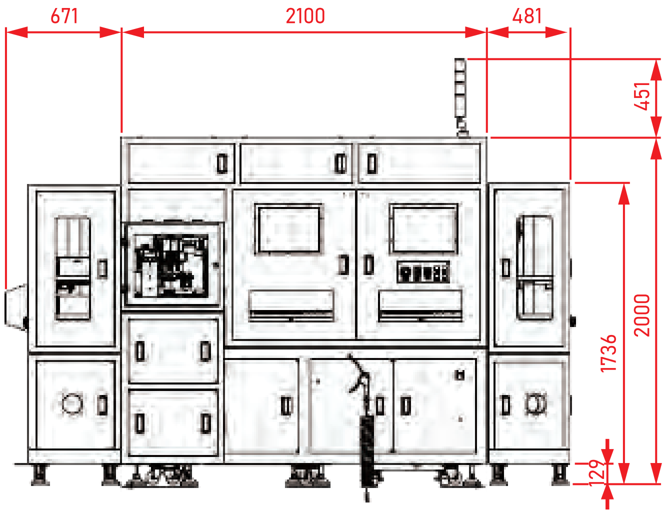
High flexibility load-unload design

- Both Stack and Slot magazine loader are available for customized selection

Machine Layout





Specification

Handler

Machine Size	3250x2000x2000mm
Stack Magazine Size	(L)200-300mmx(W)60-100mmx(H)300-420mm
Slot Magazine Size	(L)180-300mmx(W)60-100mmx(H)140-150mm
Warpage	≦10mm

Others

Handler	3∮AC220V±10% 50/60Hz, 40A
MTBA	>120 mins
MTBF	>168 hrs
Marking Accuracy	±50um
Change over time	10 mins
Air pressure	0.4~0.6 MPa (4~6 kg / cm²), Static pressure ≧2000mmH2O
Dust collection	Flow≧3.2 m³/min

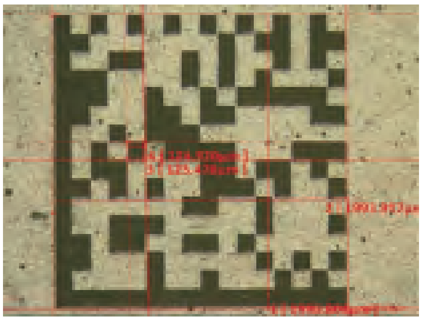
Laser

Laser Type	IR, Green	**Wave Length**	1064/532nm
Laser Medium	Nd: YV04 End Pumped	**Pulse Frequency**	15-200KHz
Marking Type	Programmable Pen-writing	**High Speed**	1000 Characters /sec
Cooling Type	Air / Water	**Spot Size**	40 - 75um
Warranty	2 years or 16000hrs	**Marking Field**	300x180nm
Auto Power Regulation	Available	**Focus Length**	255nm
Auto Download Feature	Available	**Nominal Power**	40W
-	-	**Safety Class**	65 IP

Marking Result

▲ Bare Chip

▲ Mold Compound



▲ 2DID for Lead Frame